



Qualcomm Technologies, Inc.

PM7350C Data Sheet - Overview

80-PW237-10 Rev. AC

June 27, 2024

Contents

- 1 Overview 3
 - 1.1 Device description 3
 - 1.2 Key features 3
 - 1.3 High-level block diagram and package outline 4
- 2 Revision history 5

1 Overview

1.1 Device description

The PM7350C PMIC supplements the core PMIC and the slave PMIC to integrate all wireless handset power management, general housekeeping, IC-level interface, and user interface support functions into an integrated solution.

For the complete features and system specifications, see [PM7350C Data Sheet \(80-PW237-1\)](#).

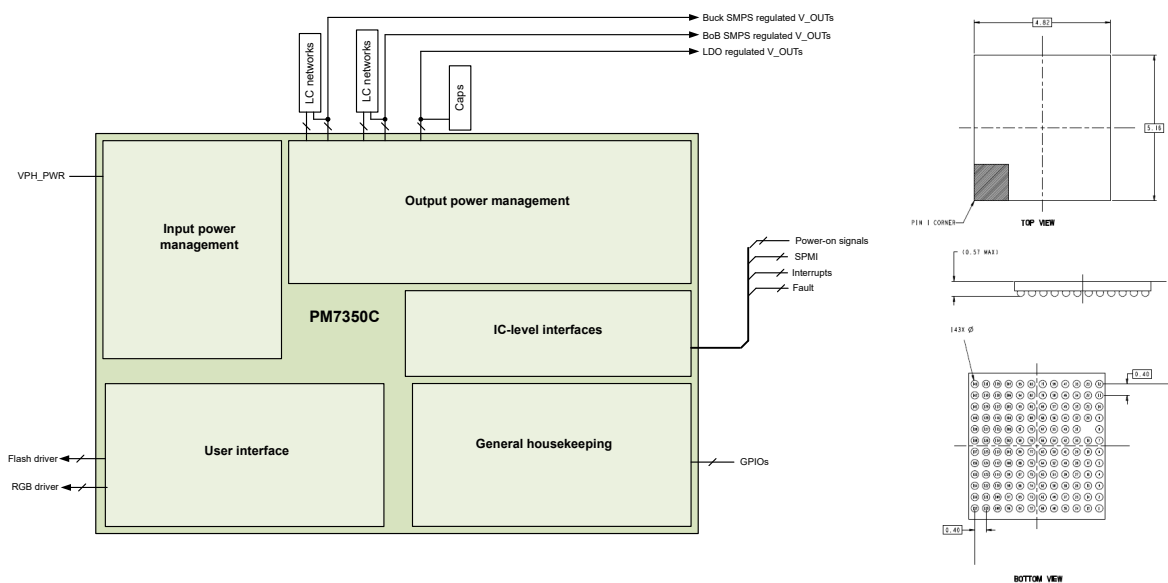
1.2 Key features

- Nine fast transient SMPS and one high frequency SMPS regulator
- Thirteen low-dropout (LDO) linear regulators
- System rail buck-or-boost (BoB) SMPS regulator
- RGB LED drivers and camera flash drivers
- Over temperature protection (OTP)
- System power management interface (SPMI)
- Nine GPIOs

Package

- 143-pin fanout wafer-level nanoscale package (FOWNSP)
- Package size: 4.82 mm × 5.16 mm × 0.57 mm with 0.40 mm pitch

1.3 High-level block diagram and package outline



2 Revision history

Revision	Date	Description
AC	June 2024	Optimized figure for dark mode
AB	April 2024	Package: Added package details
AA	March 2024	Initial release

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